## EAST Search History

| Ref<br># | Hits | Search Query  | DBs   | Default<br>Operator | Plurals | Time Stamp          |
|----------|------|---|---|---------------------|---------|---------------------|
| S2       | 4    | ((NAOMI) near2 (YONEMURA)).INV.   | US-PGPUB;<br>USPAT; USOCR   | ADJ                 | ON      | 2008/06/01<br>16:40 |
| S3       | 1    | ((KATUNORI) near2 (YASHIMA)).INV.   | US-PGPUB;<br>USPAT; USOCR   | ADJ                 | ON      | 2008/06/01<br>16:42 |
| S4       | 2    | ((YOSHIHIKO) near2 (TSUJIMURA)).<br>INV.  | US-PGPUB;<br>USPAT; USOCR   | ADJ                 | ON      | 2008/06/01<br>16:42 |
| S5       | 1    | ((HIDENORI) near2 (ISHIKURA)).INV.  | US-PGPUB;<br>USPAT; USOCR   | ADJ                 | ON      | 2008/06/01<br>16:43 |
| S6       | 29   | ((TAKASHI) near2 (SAIKI)).INV.  | US-PGPUB;<br>USPAT; USOCR   | ADJ                 | ON      | 2008/06/01<br>16:43 |
| S9       | 5    | denki.as. and (metal near1 circuit<br>near3 (board or substrate)).clm.  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ                 | ON      | 2008/06/01<br>16:45 |
| S15      | 71   | hybrid near1 (integrated circuit or IC)<br>and resin near3 inorganic near1 filler   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ                 | ON      | 2008/06/01<br>16:55 |
| S27      | 65   | circuit near1 board and hybrid near1<br>(integreated circuit or IC) and inorganic<br>near3 fill\$3  | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ                 | ON      | 2008/06/02<br>16:34 |
| S36      | 134  | resin near3 inorganic with metal near1<br>plate   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ                 | ON      | 2008/06/02<br>16:58 |
| S45      | 398  | resin near5 inorganic filler with (PCB or<br>(metal or circuit or printed) near3<br>board or metal plate)   | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ                 | ON      | 2008/06/02<br>17:21 |
| S49      | 12   | ((361/748,750,761,764,783) or<br>(257/787,E21.504,E23.004,E23.036,<br>E23.066,E23.092) or<br>(174/250,251,258)).ccls. and hybrid<br>near1 (integrated circuit or IC) and<br>resin near5 inorganic near1 fill\$3 | US-PGPUB;<br>USPAT;<br>USOCR; FPRS;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | ADJ                 | ON      | 2008/06/02<br>17:46 |

6/3/2008 4:12:50 PM

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